



Lead-free, colophony free, no-clean solder wire

Description:

Interflux[®] NH 1 for lead-free alloys is a colophony free activated no-clean solder wire. It has been developed to provide fast and repeatable soldering results on a wide range of base materials and finishes.

NH1 works very well on brass and oxidized and degraded surfaces.

The solder wire exhibits fast and excellent wetting combined with very low spattering.

It is particularly suitable for high throughput applications where a safe and reliable solder joint needs to be formed.

NH 1 solder wire can be used in both hand soldering and automated soldering processes, including laser soldering.

NH1 is activated with a low amount of halides and is classified as RE L1 according to IPC and EN-standards. It provides safe and reliable no-clean residues.



Products pictured may differ from the product delivered



Key properties

- Colophony free
- Fast wetting
- Low spattering
- High repeatability
- High throughput
- Works very well on brass
- For degraded and oxidised surfaces
- Suitable for laser soldering

Availability

Flux type: NH 1
Flux content: 1,6 and 2,2% w/w

alloy
Sn95,5Ag3,8Cu0,7
Sn96,5Ag3Cu0,5
Sn99Ag0,3Cu0,7
Sn99,3Cu0,7
Other alloys upon request

melting point	diameters							
	0,35	0,50	0,70	1,00	1,20	1,50	2,00	
+/-217°C	●	●	●	●	●	●	●	
+/-217°C	●	●	●	●	●	●	●	
+/- 217°C-227°C	●	●	●	●	●	●	●	
+/- 227°C	●	●	●	●	●	●	●	

● = available

● = upon request

Other diameters upon request





Work Instructions

Manual soldering

The advised working temperature is between 320°C and 390°C. For more dense metals like Nickel, the temperature may be elevated to 420°C.

The use of a good soldering station is important. Use a soldering station with a short response time and with enough power for your application.

Choose the correct soldering tip: to reduce the thermal resistance, it is important to create a large contact area with the surfaces to be soldered.

Heat up both the surfaces simultaneously. Slightly touch with the solder wire, the point where soldering tip and the surfaces to be soldered meet (the small quantity of sol-

der ensures a drastic lowering of the thermal resistance). Add subsequently without interruption, the correct amount of solder close to the soldering tip without touching the tip. This will reduce the risk on flux spitting and premature flux consumption.

Handling

Storage

Store the solder wire in a clean environment at ambient temperature.

Handling

To avoid spool and wire damage, handle package with care.

Safety

Please always consult the safety datasheet of the product.

Test results

Conform EN 61190-1-3(2007) and IPC J-STD-004(A)

Property	Result	Method
Chemical		
flux designator	RE L1	J-STD-004A
qualitative copper mirror	pass	J-STD-004A IPC-TM-650 2.3.32D
qualitative halide		
silver chromate (Cl, Br)	pass	J-STD-004A IPC-TM-650 2.3.33D
spot test (F)	pass	J-STD-004A IPC-TM-650 2.3.35.1
quantitative halide	< 0,5%	J-STD-004A IPC-TM-650 2.3.35
Environmental		
SIR test	pass	J-STD-004A IPC-TM-650 2.6.3.3B
qualitative corrosion, flux	pass	J-STD-004A IPC-TM-650 2.6.15



Packaging

Spools of 500g

Trade name: NH 1 (type REL1) Lead-Free, No-Clean Solder Wire

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